



FORM PTO-1449

INFORMATION DISCLOSURE CITATION

Attorney Docket:
4024-4021
Serial No.:
09/897,158

Applicant:
Dudoff et al.

Filing Date:
June 29, 2001
Group Art Unit:
2814

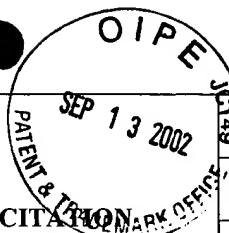
U.S. PATENT DOCUMENTS

Examiner Initial	Patent Number	Publication Date	Name	Class	Sub-Class	Filing Date
Dale	4,533,833		Copeland et al.			August 6, 1985
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	Pub. No. US2001 0081773		Inoue et al.			June 27, 2002

Examiner	<i>Dale Witz</i>	Date Considered	<i>6 Nov 02</i>
EXAMINER:	Initial if reference considered, whether or not citation is in conformance with MPEP §609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to Applicant.		

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FOREIGN PATENT DOCUMENTS

Examiner Initial	Patent Number	Publication Date	Country	Class	Sub-Class	Translation
						<input type="checkbox"/> Yes <input type="checkbox"/> No
						<input type="checkbox"/> Yes <input type="checkbox"/> No
						<input type="checkbox"/> Yes <input type="checkbox"/> No

OTHER DOCUMENTS (continued)

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✓ Ohsaki, T., "Electronic Packaging in the 1990's -A Perspective From Asia", IEEE Transactions On Components, Hybrids, And Manufacturing Technology, Vol. 14, No. 2, pages 254-261, June 1991.
✓ Pommerenig, D.H. et al., "Hybrid silicon focal plane development: an update", SPIE, Vol. 267, pages 23-30, 1981.
✓ Pu, R. et al., "Comparison of Techniques for Bonding VCSELs Directly to ICs", SPIE Vol. 3490, pages 498-501, June 2005.
✓ Pu, R. et al., "Hybrid Integration of VCSELs to Foundry Fabricated Smart Pixels", IEEE/LEOS Spring Meetings, pages 25 and 26, 1997.
✓ Sasaki, J. et al., "Self-aligned Assembly Technology for Optical Devices Using AuSn Solder Bumps Flip-Chip Bonding", pages 260-261.

Examiner

Douglas Wiles

Date Considered

6 nov 02

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